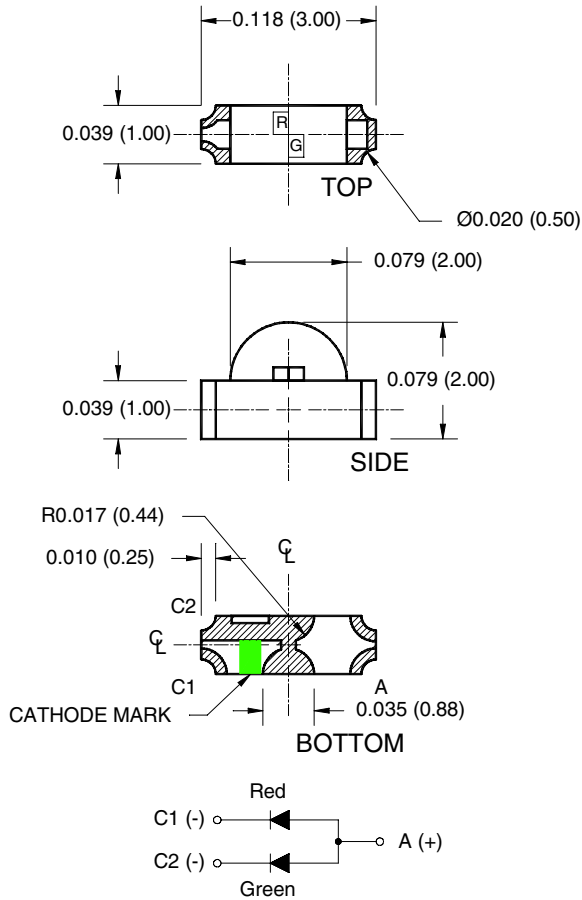


PACKAGE DIMENSIONS

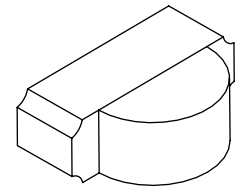


AllnGaP Red / AllnGaP Green

QTLP610C-RAG

FEATURES

- Ultra-miniature
- Water clear optics
- Moisture-proof packaging
- Available in 0.315" (8mm) width tape on 7" (178mm) diameter
- Compatible with IR and vapor phase reflow solder processes



DESCRIPTION

This bi-color surface mount lamp is designed to fit industry standard profile and footprint. The low profile, right angle mounting is ideal for side and multicolor illuminations.

ABSOLUTE MAXIMUM RATINGS (T_A = 25°C unless otherwise specified)

Parameter	QTLP610C-RAG		Units
	AllnGaP Red / AllnGaP Green		
Continuous Forward Current - I _F	30/30		mA
Peak Forward Current - I _F (f = 1.0 KHz, Duty Factor = 1/10)	160/160		mA
Reverse Voltage - V _R (I _R = 10 μA)	5/5		V
Power Dissipation - P _D	60/60		mW
Operating Temperature - T _{OPR}	-40 to +85		°C
Storage Temperature - T _{STG}	-40 to +100		°C
Lead Soldering Time - T _{SOL}	260 for 5 sec		°C

AllnGaP Red / AllnGaP Green

QTLP610C-RAG

ELECTRICAL / OPTICAL CHARACTERISTICS (T_A = 25°C)

Part Number	QTLP610C-RAG AllnGaP Red / AllnGaP Green	Condition
Luminous Intensity (mcd)		I _F = 20 mA
Minimum	20/15	
Typical	45/25	
Forward Voltage (V)		I _F = 20 mA
Maximum	2.4/2.4	
Typical	2.0/2.0	
Wavelength (nm)		I _F = 20 mA
Peak	630/575	
Dominant	624/573	
Spectral Line Half Width (nm)	20/20	I _F = 20 mA
Viewing Angle (°)	120/120	I _F = 20 mA

TYPICAL PERFORMANCE CURVES

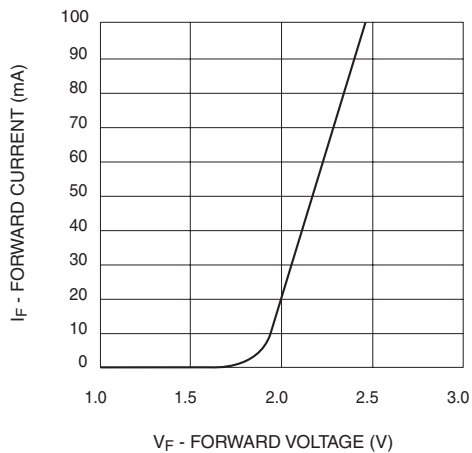


Fig. 1 Forward Current vs. Forward Voltage

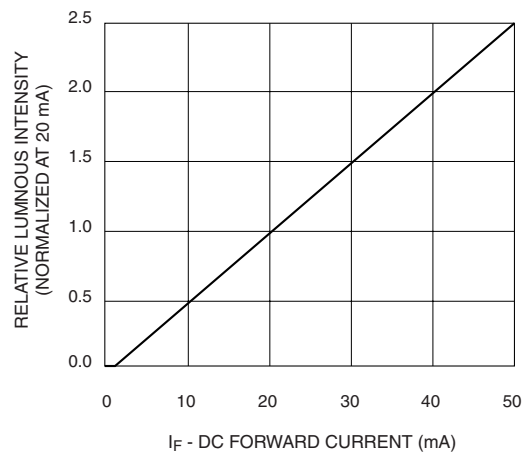


Fig. 2 Relative Luminous Intensity vs. DC Forward Current

TYPICAL PERFORMANCE CURVES

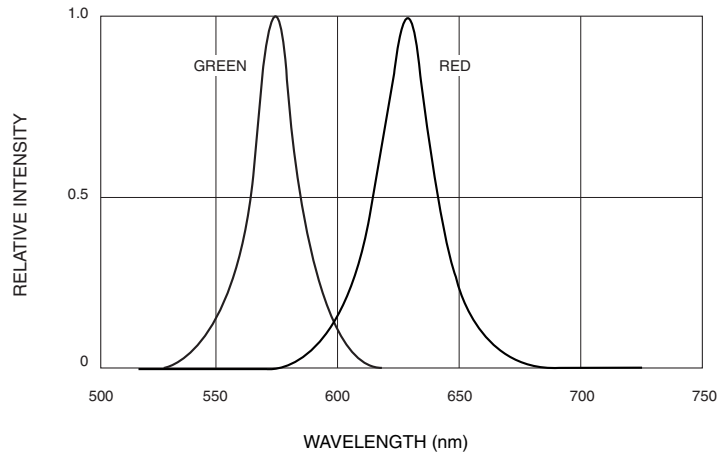
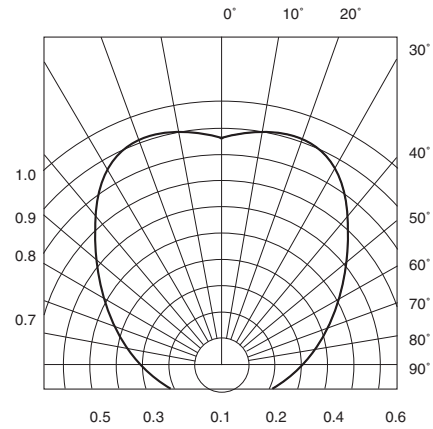
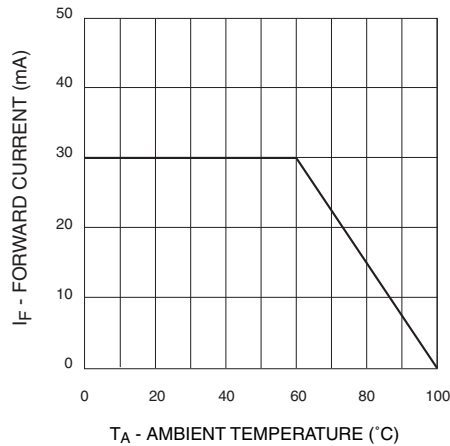


Fig. 3 Relative Intensity vs. Peak Wavelength



REL. LUMINOUS INTENSITY (%)

Fig. 4 Radiation Diagram



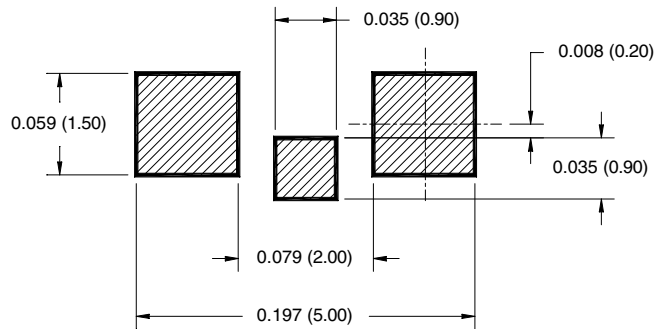
T_A - AMBIENT TEMPERATURE (°C)

Fig. 5 Current Derating Curve

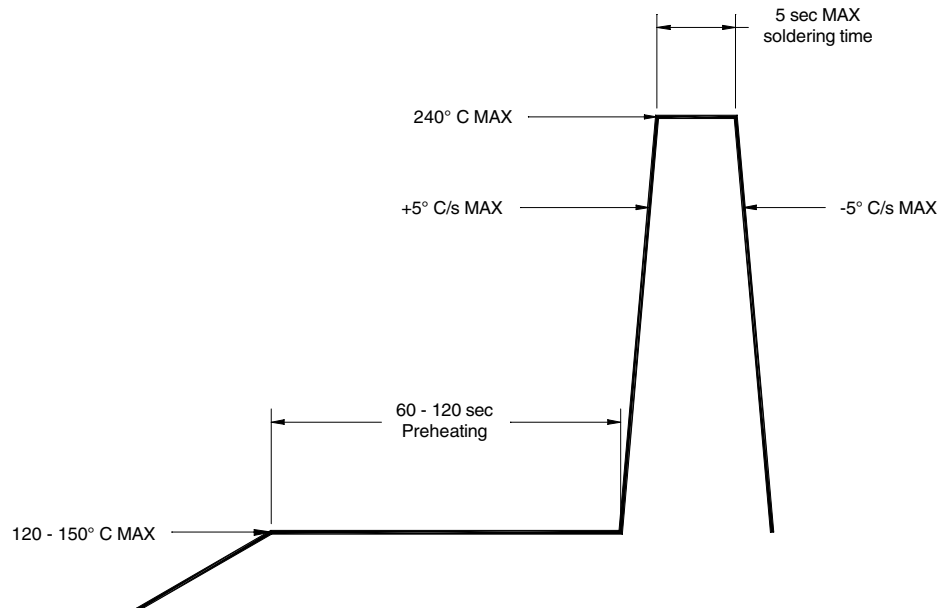
AllnGaP Red / AllnGaP Green

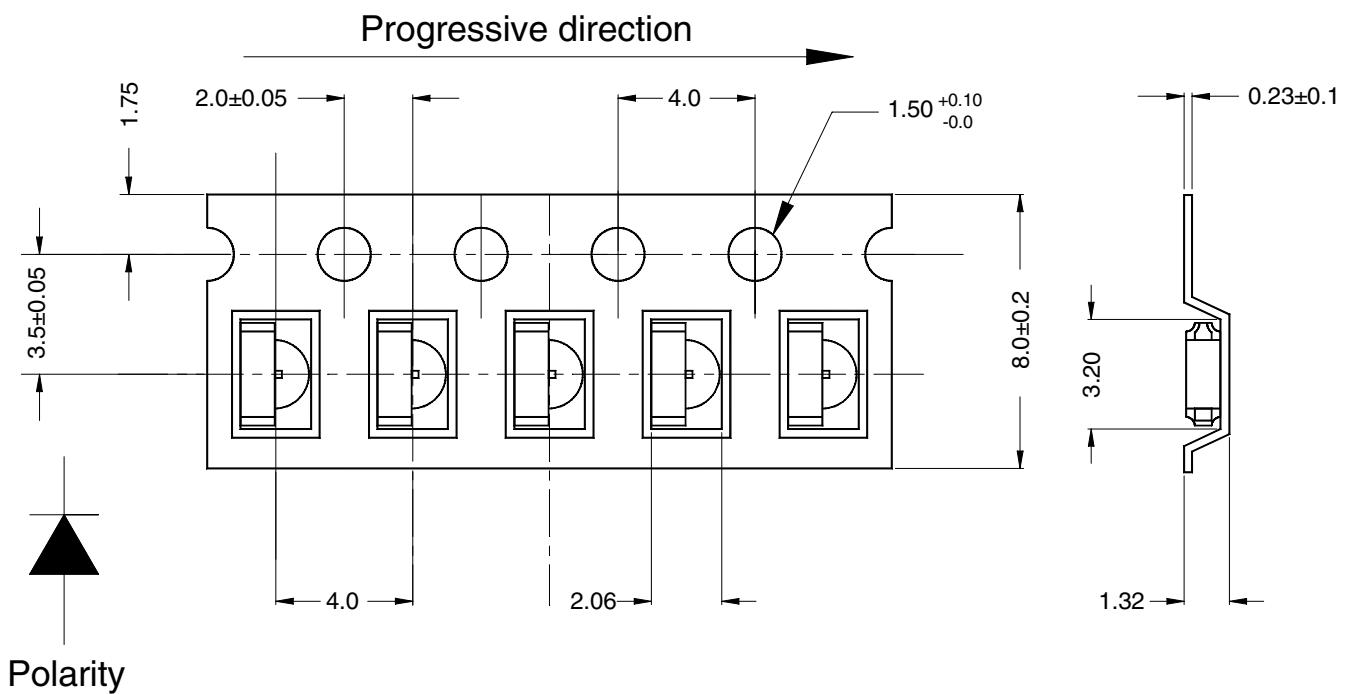
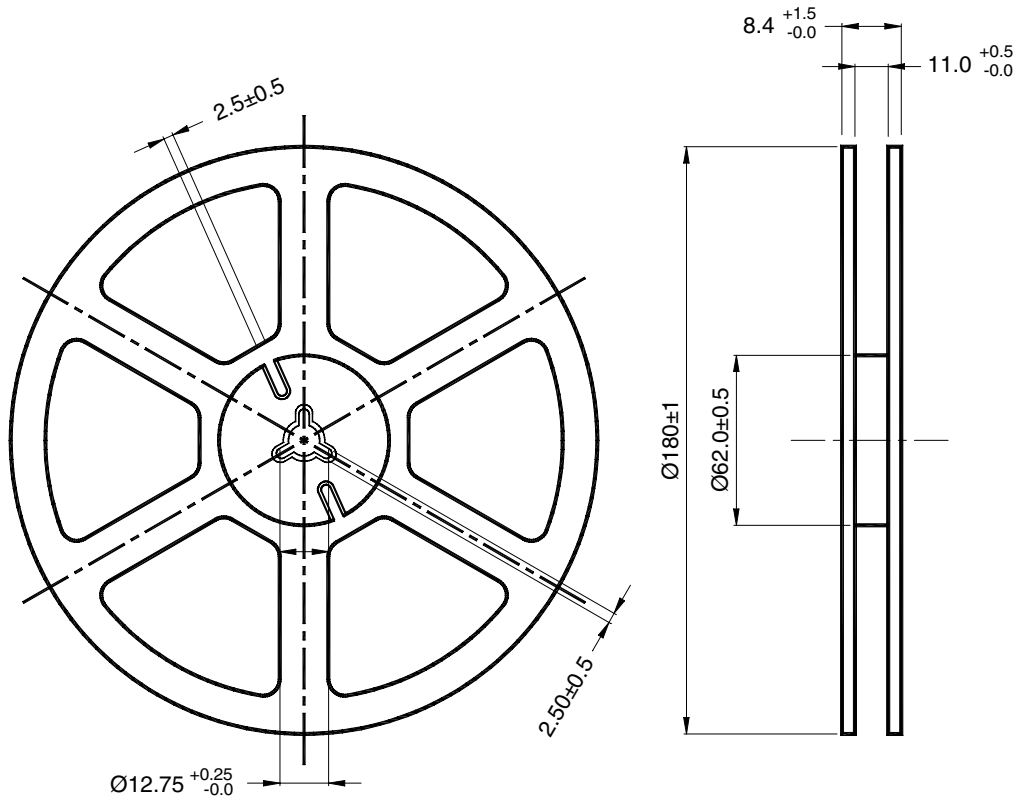
QTLP610C-RAG

RECOMMENDED PRINTED CIRCUIT BOARD PATTERN



RECOMMENDED IR REFLOW SOLDERING PROFILE





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